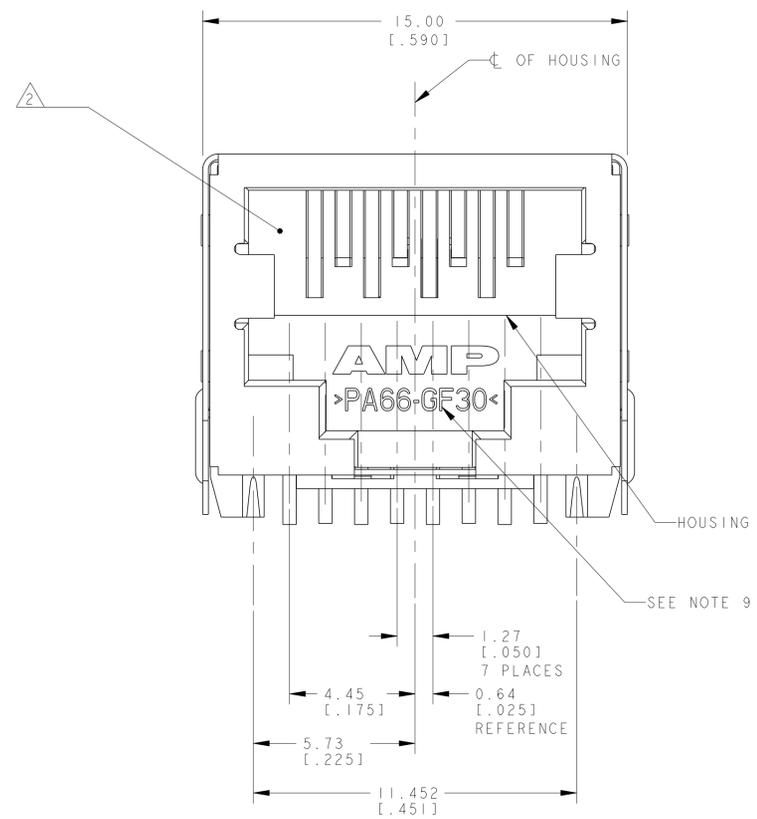
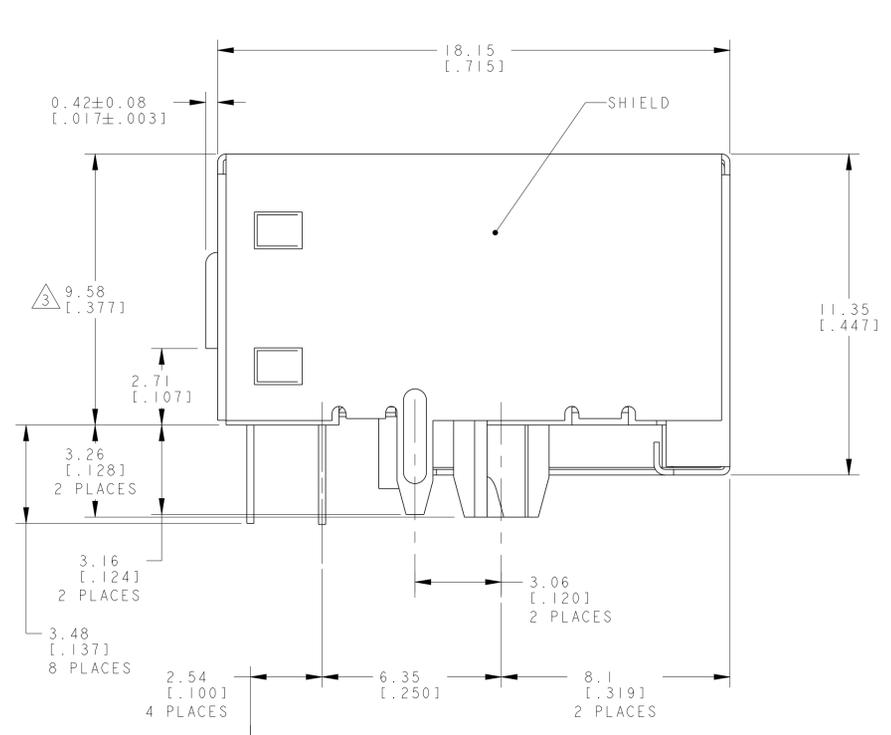
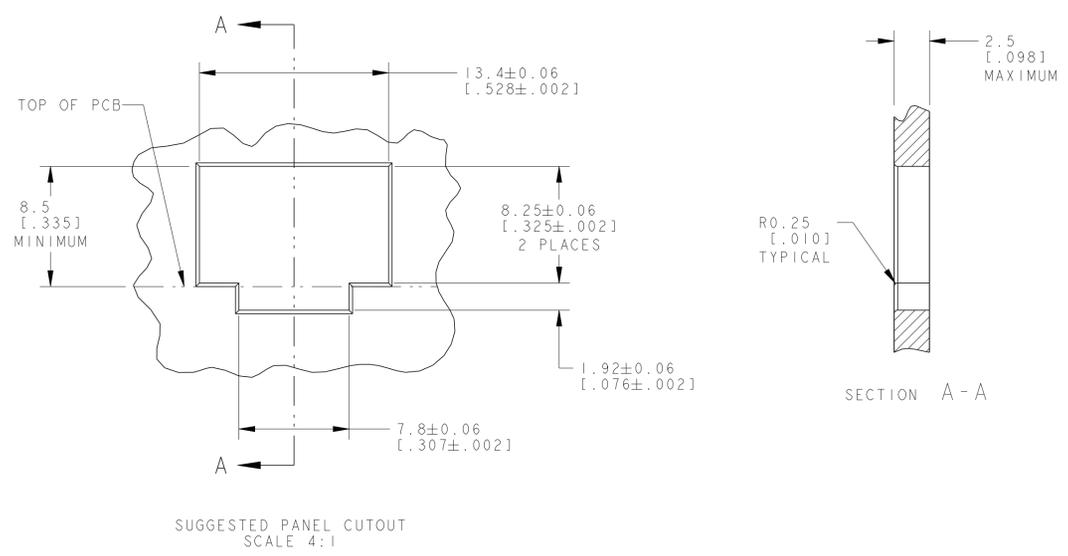
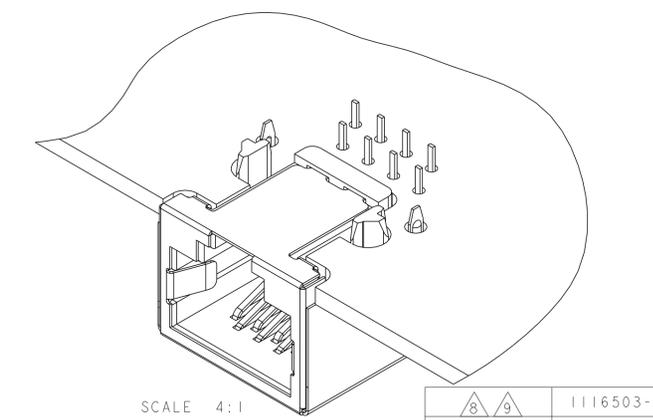
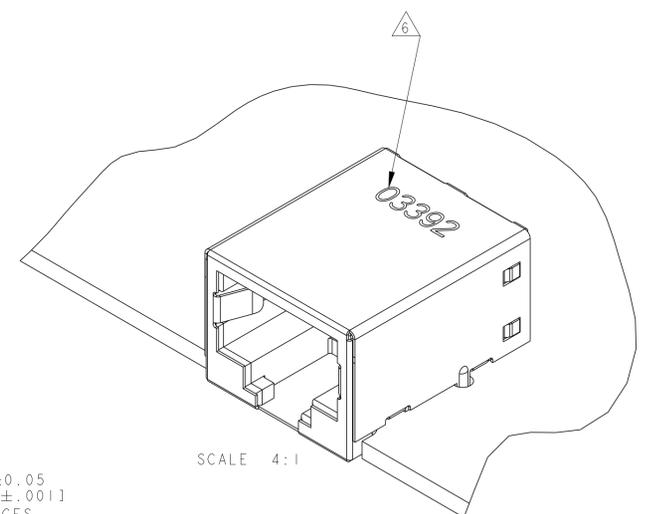
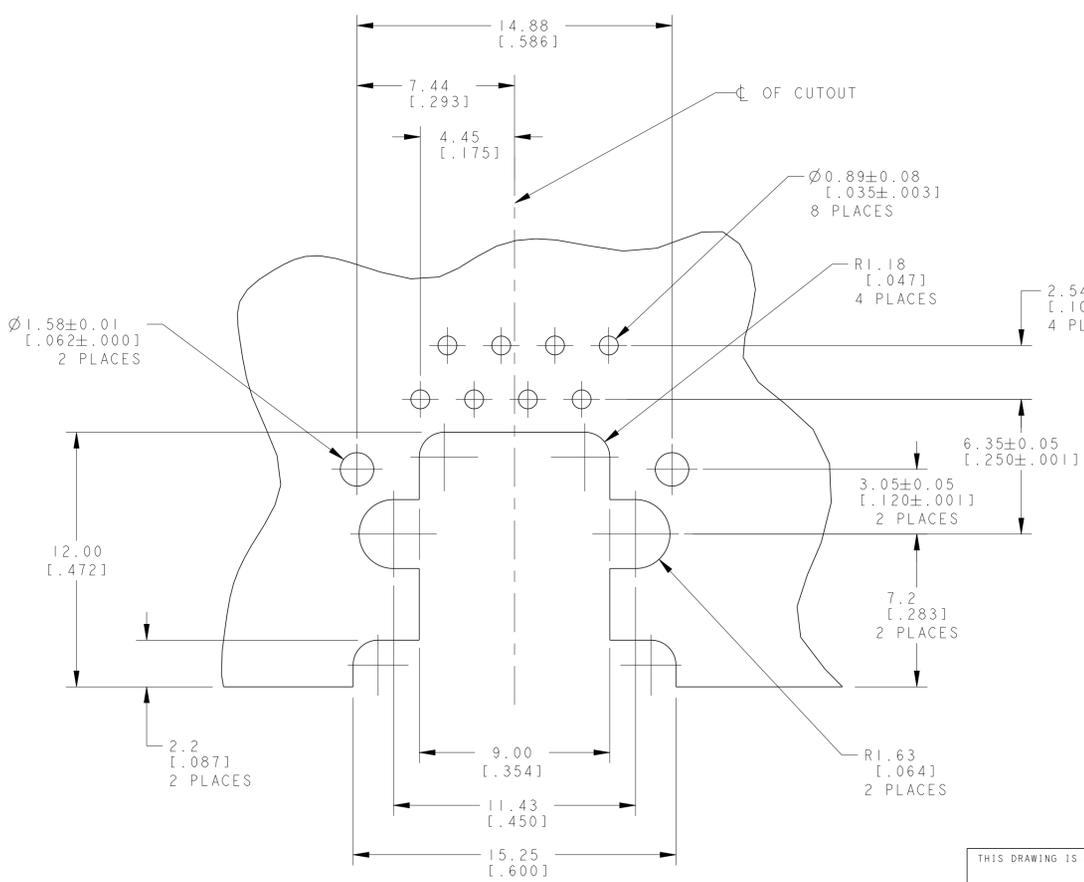
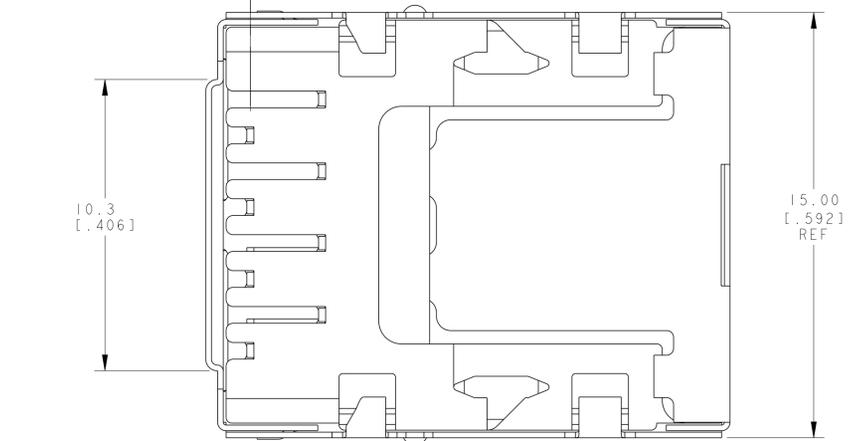


LOC	DIST	REVISIONS					
		P	LTN	DESCRIPTION	DATE	OWN	APVD
AA	22	P		REVISED PER ECO-14-015233	27APR2015	LL	SH
		R		ECO-16-011601	05AUG2016	LL	SH
		R1		REVISED AS PER ECR-23-169440	19APR2023	KV	WH



- 1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, TERMINALS - 0.25[.01] THICK PHOSPHOR BRONZE PLATED WITH 3.81um[.000150] MINIMUM THICK BRIGHT TIN-LEAD IN SOLDER AREA, 1.27um[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27um[.000050] MINIMUM THICK NICKEL. SHIELD - 0.1[.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0um (.000079-.000157) THICK TIN OVER 1.27 um (.000050) MIN THICK NICKEL.
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3 THIS DIMENSION REPRESENTS THE TOTAL HEIGHT OF THE CONNECTOR FROM THE TOP OF THE PC BOARD.
- 4 PACKAGED 66 ASSEMBLIES PER PVC TRAY, 396 PER BOX.
- 5 DIELECTRIC WITHSTANDING VOLTAGE BETWEEN SHIELD AND TERMINAL IS 1500 VAC.
- 6 MANUFACTURING DATE CODE:
ORIENTED AND LOCATED APPROXIMATELY AS SHOWN. LASER PRINTING.
TEXT HEIGHT APPROXIMATELY 2MM.
FIRST 2 DIGITS - LAST 2 DIGITS OF YEAR
NEXT 2 DIGITS - MANUFACTURING WORK WEEK
LAST DIGIT - DAY OF WEEK WITH SUNDAY = 1
- 7 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, TERMINALS - 0.25[.01] THICK PHOSPHOR BRONZE PLATED WITH 3.81um[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27um[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27um[.000050] MINIMUM THICK NICKEL. SHIELD - 0.1[.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 1.27um[.000050]min THICK NICKEL AND HOT TIN DIP ON PCB ROUND TABS.
- 8 MATERIAL: HOUSING - POLYESTER LCP, NATURE, UL 94V-0, TERMINALS - 0.25[.01] THICK PHOSPHOR BRONZE PLATED WITH 3.81um[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27um[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27um[.000050] MINIMUM THICK NICKEL. SHIELD - 0.1[.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 1.27um[.000050]min THICK NICKEL AND HOT TIN DIP ON PCB ROUND TABS.
- 9 FOR 1116503-3 MATERIAL MARK: >LCP-GF30<.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SCALE 6:1

8	9	1116503-3
7		1116503-2
6		1116503-1
MATERIAL / FINISH		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

OWN: J. AHERON 07APR99
 CHK: D. KEMPKA 07APR99
 APVD: D. KEMPKA 07APR99

TE Connectivity

MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, 10mm WITHOUT PANEL TABS

108-1163
 114-2048
 3.49 grams
 A100779 ©=1116503

SCALE 1:1 SHEET 1 OF 1 REV 1